

## NOTES:

## MATERIAL:

- 1.HOUSING MATERIAL :GLASS FILLED POLYESTER(UL94V-0).  
 2.CONTACT MATERIAL :PHOSPHOR BRONZE  $\varnothing 0.46$ mm (C5100).  
 3.PLATING :GOLD PLATING OVER NICKEL.  
 4.SHIELD: COPPER ALLOY 0.20mm THICKNESS PLATING NI.

## ELECTRICAL:

- 1.VOLTAGE RATING :125 VAC RMS.  
 2.CURRENT RATING :1.5 AMP.  
 3.CONTACT RESISTANCE :50 MILLIOHMS MAX.  
 4.INSULATION RESISTANCE :500 MEGOHMS MIN @ 500V DC.  
 5.DIELECTRIC WITHSTANDING  
 RESISTANCE :1000V AC RMS 50Hz. 1MIN.

## MECHANICAL:

- 1.DURRABILITY :750 CYCLES MIN.  
 2.PCB RETENTION PRE-SOLDER :1 LB MIN.

## ENVIRONMENTAL:

- 1.STORAGE : $-40^{\circ}\text{C}$  TO  $+85^{\circ}\text{C}$ .  
 2. OPERATION :  $0^{\circ}\text{C}$  TO  $70^{\circ}\text{C}$ .

COMPLIES WITH MODULAR PLUG CONFORMING TO

FCC PART 68, SUBPART F.

## PART NUMBER:

**A58B-03108302XX3X**59 SERIES  
PCB JACK  
(59系列PCB接口)SHIELD (屏蔽壳) :  
1-W/O SHIELD (非屏)  
2-HALF SHIELD (半包)  
3-FULL SHIELD (全包)PORTS (插口) :  
1-1X1 (一口). 2-1X2 (二口)  
4-1X4 (四口). 5-1X5 (五口)  
6-1X6 (六口). 8-1X8 (八口)  
POSITIONS (金针位置) :

4-4POSITIONS (4P)

6-6POSITIONS (6P)

8-8POSITIONS (8P)

0-10POSITIONS (10P)

CONTACTS (金针根数) :

1-2. 3. 4. 7PIN. 2-2CONTACTS (2C)

4-4CONTACTS (4C). 6-6CONTACTS (6C)

8-8CONTACTS (8C). 0-10CONTACTS (10C)

PEG/TAB (边定位铁脚) :

0-W/O PEG (无铁脚). 1-FRONT PEG 3.05 (前脚3.05)

2-FRONT PEG3.68 (前脚3.68). 3-FRONT PEG4.57 (前脚4.57)

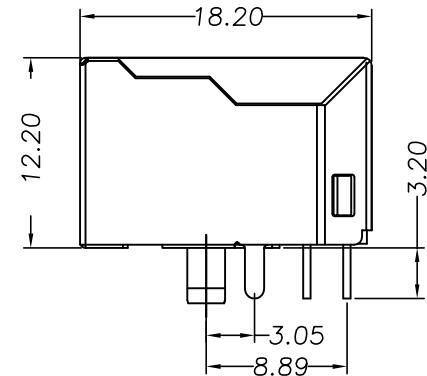
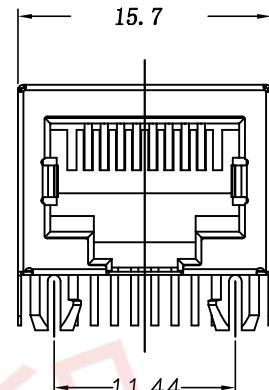
4-BACK PEG3.05 (后脚3.05)

1-PBT. 2-NYLON66 (尼龙66).  
3-NYLON46 (尼龙46). 4-ABSEMI (弹片) :1-W/O EMI (无弹片).  
2-W/ EMI (带弹片)BACK PEG (后背铁脚) :  
0-W/O BACK PEG (无后背铁脚).  
1-1BACK PEG (1个后背铁脚).  
2-2BACK PEG (2个后背铁脚).  
3-3BACK PEG (3个后背铁脚)

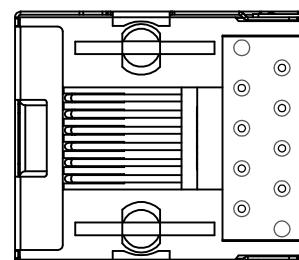
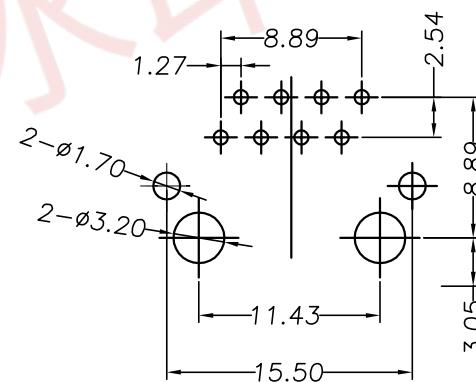
Autodesk 教育版产品制作

REVISION RECORD

REV	ECO	DESCRIPTION	DRFT	CHKD
A		原始版本	XIANWENZ 08.08.04	



PEG/TAB



DETACHED LISTS	MM — 范公差栏 — — — —	设计 zhangwei	日期 10.03.10	浙江创都电子科技有限公司	
	审核	日期		系列	名称
	批准 zhang ke	日期 10.03.10	RJ5803B-10P8C-BKKHJ		
	材料:			系列	
	角度 ± 0.01°	数量:		图号:	
		表面处理:		料号:	
		比例: 1:1	不按比例	A4	A
			共 X 页 第 Y 页		